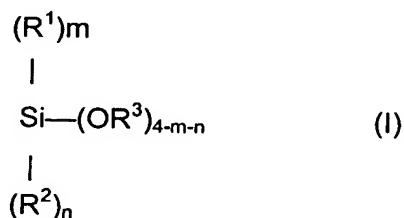


Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended) A composition comprising (a) a thermally decomposable polymer which exhibits a weight loss at 400°C of 80% or more based on the weight at 150°C as measured by a thermogravimetric analysis in which the temperature is elevated from 30°C or lower at a temperature elevation rate of 20°C/mm under an air stream and (b) a siloxane oligomer dissolved in (c) an organic solvent.
2. (previously presented) The composition according to Claim 1, wherein (b) the siloxane oligomer is a compound having a non-hydrolyzable organic group.
3. (previously presented) The composition according to Claim 2, wherein (b) the siloxane oligomer is a hydrolytic condensation product of an alkoxysilane represented by the following formula (I):



wherein R^1 and R^2 each represent a non-hydrolyzable group which may be the same or different; R^3 represents an alkyl group having 1 to 6 carbon atoms; and each

of m and n is an integer selected from 0 to 3 so that m and n satisfy the relationship:

$$0 \leq m + n \leq 3.$$

4. (previously presented) The composition according to Claim 3, wherein (a) the thermally decomposable polymer is a polymer which exhibits a weight loss at 250°C of less than 5% based on the weight 25 at 150°C as measured by a thermogravimetric analysis in which the temperature is elevated from 30°C or lower at a temperature elevation rate of 20°C/mm under an air stream.

5. (canceled)

6. (currently amended) The composition according to Claim-~~5~~ 1, wherein (a) the thermally decomposable polymer is a fluorine-free polymer.

7. (currently amended) The composition according to claim-~~5~~ 1, wherein (a) the thermally decomposable polymer is a methacrylate polymer or an acrylate polymer.

8. (currently amended) A composition comprising

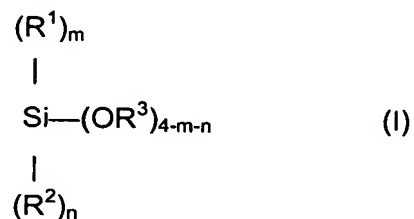
(a) a thermally decomposable polymer which exhibits a weight loss at 400°C of 80% or more based on the weight at 150°C as measured by a thermogravimetric analysis in which the temperature is elevated from 30°C or lower at a temperature elevation rate of 20°C/mm under an air stream.

(b) a siloxane oligomer, and

(c) an organic solvent in which both of said components (a) and (b) are soluble.

9. (previously presented) The composition according to Claim 8, wherein (b) the siloxane oligomer is a compound having a non-hydrolyzable organic group.

10. (previously presented) The composition according to Claim 9, wherein (b) the siloxane oligomer is a hydrolytic condensation product of an alkoxy silane represented by the following formula (I):



wherein R^1 and R^2 each represent a non-hydrolyzable group which may be the same or different; R^3 represents an alkyl group having 1 to 6 carbon atoms; and each of m and n is an integer selected from 0 to 3 so that m and n satisfy the relationship: $0 \leq m + n \leq 3$.

11. (previously presented) The composition according to Claim 10, wherein (a) the thermally decomposable polymer is a polymer which exhibits a weight loss at 250°C of less than 5% based on the weight at 150°C, as measured by a thermogravimetric analysis in which the temperature is elevated from 30°C or lower at a temperature elevation rate of 20°C/mm under an air stream.

12. (canceled)

13. (currently amended) The composition according to Claim ~~12~~8, wherein (a) the thermally decomposable polymer is a fluorine-free polymer.

14. (currently amended) The composition according to Claim ~~12~~8, wherein (a) the thermally decomposable polymer is a methacrylate polymer or an acrylate polymer.

15. (previously presented) A method for forming a low-permittivity film which comprises applying the composition according to Claim 1 to a substrate to form a composite film comprising the thermally decomposable polymer and the siloxane oligomer evenly compatibilized therewith, and then heating the resulting film to condense the siloxane oligomer and remove the thermally decomposable polymer.

16. (previously presented) A method for forming a low-permittivity film which comprises applying the composition according to Claim 1 to a substrate to form a composite film comprising the thermally decomposable polymer and the siloxane oligomer evenly compatibilized therewith, subsequently conducting a first heating step in which the siloxane oligomer is crosslinked while keeping the thermally decomposable polymer remaining in the film, and then conducting a second heating step in which the thermally decomposable polymer is removed.

17. (previously presented) The method according to Claim 16, wherein said first heating step is conducted at a temperature of 80 to 350°C, and wherein said second heating step is conducted at a temperature of 350 to 500°C.

18. (previously presented) A low-permittivity film formed by the method according to Claim 15.

19. (previously presented) A low-permittivity film formed by the method according to Claim 16.

20. (previously presented) A low-permittivity film formed by the method according to Claim 17.

21. (previously presented) An electronic part having the low-permittivity film according to Claim 18.

22. (previously presented) An electronic part having the low-permittivity film according to Claim 19.

23. (previously presented) An electronic part having the low-permittivity film according to Claim 20.

24. (currently amended) A method for forming a low-permittivity film which comprises applying the composition according to Claim ~~42~~11 to a substrate to form a composite film comprising the thermally decomposable polymer and the siloxane oligomer evenly compatibilized therewith, and then heating the resulting film to condense the siloxane oligomer and remove the thermally decomposable polymer.

25. (previously presented) A low-permittivity film formed by the method according to Claim 24.

26. (previously presented) A method for forming a low-permittivity film which comprises applying the composition according to Claim 10 to a substrate to form a composite film comprising the thermally decomposable polymer and the siloxane oligomer evenly compatibilized therewith, and then heating the resulting film to condense the siloxane oligomer and remove the thermally decomposable polymer.

27. (previously presented) A low-permittivity film formed by the method according to Claim 26.

28. (previously presented) A method for forming a low-permittivity film which comprises applying the composition according to Claim 8 to a substrate to form a composite film comprising the thermally decomposable polymer and the siloxane oligomer evenly compatibilized therewith, and then heating the resulting film to condense the siloxane oligomer and remove the thermally decomposable polymer.

29. (previously presented) A low-permittivity film formed by the method according to Claim 28.

30. (currently amended) A method for forming a low-permittivity film which comprises applying the composition according to Claim 5 4 to a substrate to form a composite film comprising the thermally decomposable polymer and the siloxane

oligomer evenly compatibilized therewith, and then heating the resulting film to condense the siloxane oligomer and remove the thermally decomposable polymer.

31. (previously presented) A low-permittivity film formed by the method according to Claim 30.

32. (currently amended) A method for forming a low-permittivity film which comprises applying the composition according to Claim ~~42~~11 to a substrate to form a composite film comprising the thermally decomposable polymer and the siloxane oligomer evenly compatibilized therewith, subsequently conducting a first heating step in which the siloxane oligomer is crosslinked while keeping the thermally decomposable polymer remaining in the film, and then conducting a second heating step in which the thermally decomposable polymer is removed.

33. (previously presented) The method according to Claim 32, wherein said first heating step is conducted at a temperature of 80 to 350°C, and wherein said second heating step is conducted at a temperature of 350 to 500°C.

34. (previously presented) A low-permittivity film formed by the method according to Claim 32.

35. (previously presented) A method for forming a low-permittivity film which comprises applying the composition according to Claim 10 to a substrate to form a composite film comprising the thermally decomposable polymer and the siloxane oligomer evenly compatibilized therewith, subsequently conducting a first heating

step in which the siloxane oligomer is crosslinked while keeping the thermally decomposable polymer remaining in the film, and then conducting a second heating step in which the thermally decomposable polymer is removed.

36. (previously presented) The method according to Claim 35, wherein said first heating step is conducted at a temperature of 80 to 350°C, and wherein said second heating step is conducted at a temperature of 350 to 500°C.

37. (previously presented) A low-permittivity film formed by the method according to Claim 35.

38. (previously presented) A method for forming a low-permittivity film which comprises applying the composition according to Claim 8 to a substrate to form a composite film comprising the thermally decomposable polymer and the siloxane oligomer evenly compatibilized therewith, subsequently conducting a first heating step in which the siloxane oligomer is crosslinked while keeping the thermally decomposable polymer remaining in the film, and then conducting a second heating step in which the thermally decomposable polymer is removed.

39. (previously presented) The method according to Claim 38, wherein said first heating step is conducted at a temperature of 80 to 350°C, and wherein said second heating step is conducted at a temperature of 350 to 500°C.

40. (previously presented) A low-permittivity film formed by the method according to Claim 38.

41. (currently amended) A method for forming a low-permittivity film which comprises applying the composition according to Claim 54 to a substrate to form a composite film comprising the thermally decomposable polymer and the siloxane oligomer evenly compatibilized therewith, subsequently conducting a first heating step in which the siloxane oligomer is crosslinked while keeping the thermally decomposable polymer remaining in the film, and then conducting a second heating step in which the thermally decomposable polymer is removed.

42. (previously presented) The method according to Claim 41, wherein said first heating step is conducted at a temperature of 80 to 350°C, and wherein said second heating step is conducted at a temperature of 350 to 500°C.

43. (previously presented) A low-permittivity film formed by the method according to Claim 41.

44. (previously presented) A low-permittivity film formed by the method according to Claim 39.

45. (previously presented) An electronic part having the low-permittivity film according to Claim 31.

46. (previously presented) An electronic part having the low-permittivity film according to Claim 29.

47. (previously presented) An electronic part having the low-permittivity film according to Claim 27.

48. (previously presented) An electronic part having the low-permittivity film according to Claim 25.

49. (previously presented) An electronic part having the low-permittivity film according to Claim 43.

50. (previously presented) An electronic part having the low-permittivity film according to Claim 40.

51. (previously presented) An electronic part having the low-permittivity film according to Claim 37.

52. (previously presented) An electronic part having the low-permittivity film according to Claim 34.

53. (previously presented) An electronic part having the low-permittivity film according to Claim 44.

54. (new) An electronic part according to claim 45, wherein the electronic part includes copper wiring.

55. (new) An electronic part according to claim 46, wherein the electronic part includes copper wiring.

56. (new) An electronic part according to claim 47, wherein the electronic part includes copper wiring.

57. (new) An electronic part according to claim 48, wherein the electronic part includes copper wiring.

58. (new) An electronic part according to claim 49, wherein the electronic part includes copper wiring.

59. (new) An electronic part according to claim 50, wherein the electronic part includes copper wiring.

60. (new) An electronic part according to claim 51, wherein the electronic part includes copper wiring.

61. (new) An electronic part according to claim 52, wherein the electronic part includes copper wiring.

62. (new) An electronic part according to claim 53, wherein the electronic part includes copper wiring.

63. (new) An electronic part according to claim 21, wherein the electronic part includes copper wiring.

64. (new) An electronic part according to claim 22, wherein the electronic part includes copper wiring.

65. (new) An electronic part according to claim 23, wherein the electronic part includes copper wiring.